

UNCONTROLLED DOCUMENT

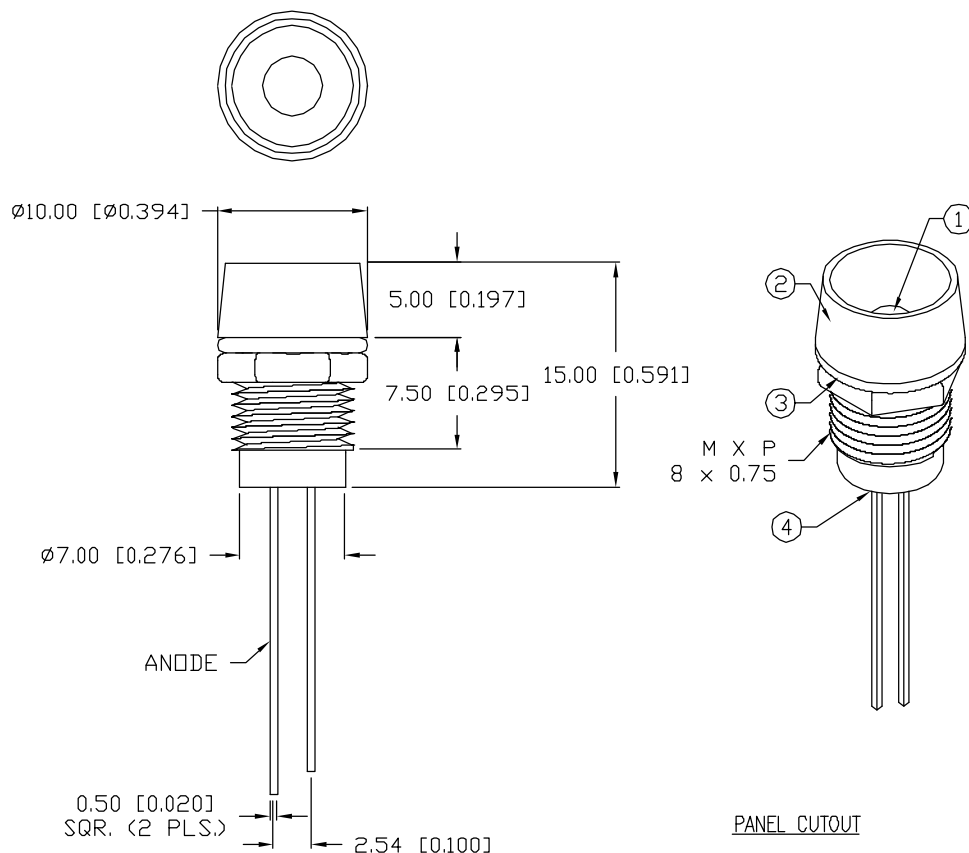
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PART NUMBER

REV.

SSI-LXR4815YD12VWR

PRELIMINARY IN P/N DIR



NOTES:

1. SSL-LX5063YD-12V, YELLOW LED.
2. SSI-LXR4815, CHROME HOUSING.
3. LXP-WA-3816, RUBBER GASKET.
4. SSH-LXH4815BSG, BLACK NYLON BUSHING. (NOT SHOWN).
5. THREAD LEADS THROUGH BUSHING, INSERT INTO HOUSING, BACKFILL WITH SILICON ADHESIVE, INSERT BUSHING INTO HOUSING. CRIMP INTO PLACE.
6. WATER RESISTANT PER NEMA STANDARD 250, SECTION 6.7.

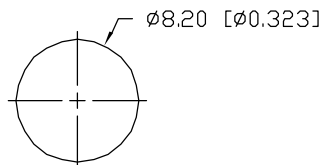
\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $V_f=12\text{V}$					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		12.0	14.0	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		10		mcd	$V_f=12\text{V}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD VOLTAGE	14	V
STEADY CURRENT	12	mA
POWER DISSIPATION	310	mW
DERATE FROM 25°C	-0.7	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

PANEL CUTOUT



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290 E. HELEN ROAD  
PALATINE, IL 60067-6976  
PHONE: +1.847.359.2790  
US WEB: www.lumex.com  
TW WEB: www.lumex.com.tw

T-5mm 585nm YELLOW LED PANEL INDICATOR,  
YELLOW DIFFUSED LENS, 12 VOLT OPERATION,  
SPASH RESISTANT.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JN	CHECKED BY:	APPROVED BY:	DATE: 01.19.09
			PAGE: 1 OF 1
			SCALE: N/A